initial thickness portion and said subsequent portion, wherein said intermediate thickness portion is fabricated utilizing a relatively mid-range carbon ion beam energy between said relatively low carbon ion beam energy and said relatively high carbon ion beam energy.

C2

17. (Once amended) A process for fabricating a magnetic media hard disk as described in claim 16 wherein said mid-range carbon ion beam energy is approximately 50 eV.

18. (Once amended) A process for fabricating a magnetic media hard disk as described in claim 17 wherein said DLC layer has a thickness of approximately 10 Å following the deposition of said initial thickness portion, and said DLC layer has a thickness of approximately 19 Å following the deposition of said intermediate thickness portion, and said DLC layer has a final thickness of approximately 25 Å following the deposition of said subsequent thickness portion.

C3

20. (Once amended) A method for fabricating a magnetic media hard disk as described in claim 13 wherein nitrogen ion species are deposited along with said carbon ion species within said subsequent thickness portion.

C4

22. (Twice amended) A method for fabricating a magnetic media hard disk comprising:

fabricating a magnetic material layer upon a material surface of a substrate;

fabricating a diamond-like carbon (DLC) layer upon said magnetic layer, wherein said DLC layer is fabricated by:

depositing carbon ion species upon said magnetic layer utilizing a relatively low carbon ion beam energy level of from approximately 10 eV to approximately 20 eV, to deposit an initial thickness portion of said DLC layer;

subsequently increasing the energy level of said carbon ion beam as the thickness of said DLC layer increases due to the deposition of said carbon ion species within said DLC layer, such that a portion of the carbon ion beam species of said increased energy level carbon ion beam become implanted within said initial thickness portion of said DLC layer, and such that another portion of said carbon ion beam species of said increased energy level carbon ion beam become deposited on top of said initial thickness portion of said DLC layer.

25. (Once amended) A method for fabricating a magnetic media hard disk as described in claim 23 wherein nitrogen ion species are implanted along with said carbon ion species within said DLC layer thickness.

Please add the following new claims:

27. A process for fabricating a magnetic media hard disk, comprising:

fabricating a magnetic media layer upon a surface material of a substrate;

fabricating a diamond-like carbon (DLC) layer including carbon ion species upon said magnetic layer, by:

fabricating an initial thickness portion of said DLC layer upon said magnetic layer utilizing a relatively low ion carbon beam energy of from approximately 10 eV to approximately 20 eV;

fabricating a subsequent thickness portion of said DLC layer upon said initial thickness portion of said DLC layer utilizing a higher carbon ion beam energy, wherein a portion of the carbon ion species of said subsequent thickness portion penetrates into said initial thickness portion and not into said magnetic media layer, and another portion of said carbon ion species of said subsequent layer are disposed on top of said initial thickness portion.

28. A process for fabricating a magnetic media hard disk as described in claim 27 including:

fabricating a further thickness portion of said DLC layer upon said subsequent thickness portion of said DLC layer utilizing a higher carbon ion beam energy, wherein a portion of the carbon ion species of said further thickness portion penetrate into said subsequent thickness portion and into said initial thickness portion, and not into said magnetic media layer, and wherein another portion of said carbon ion species of said further thickness layer are disposed on top of said subsequent thickness portion.

29. A process for fabricating a magnetic media heard disk as described in claim 27 wherein said carbon ion beam energy of said subsequent thickness portion is approximately 50 eV and wherein said carbon ion beam energy of said further thickness portion is approximately 100 eV.